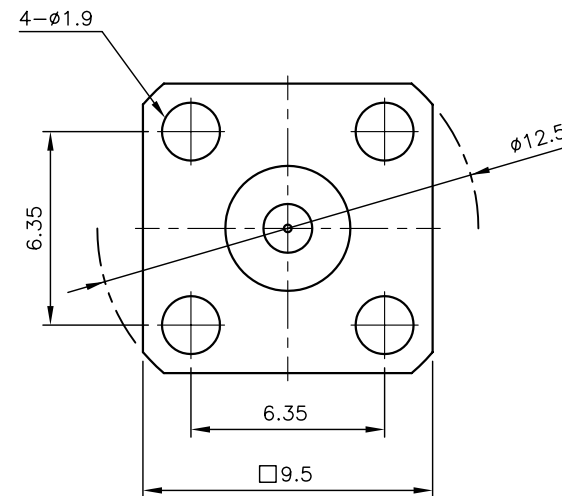
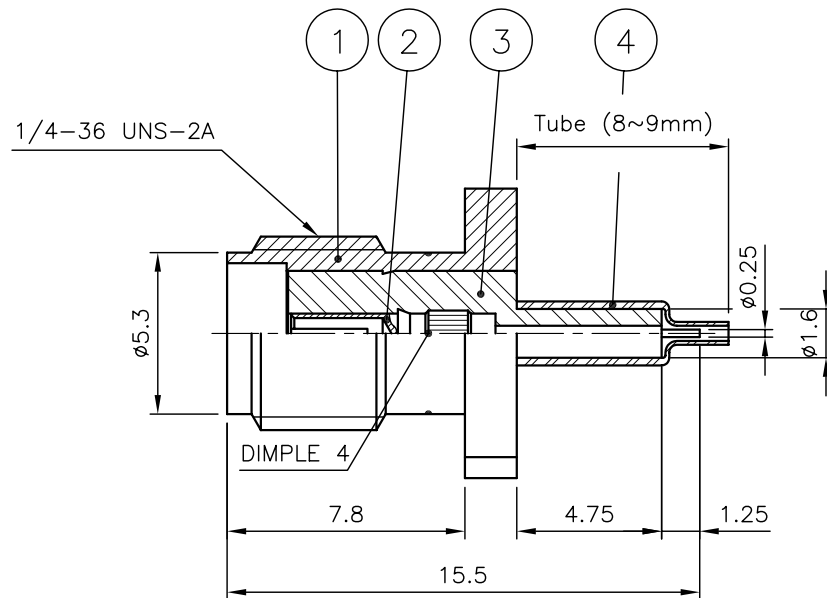


1 2 3 4 5 6

REVISION

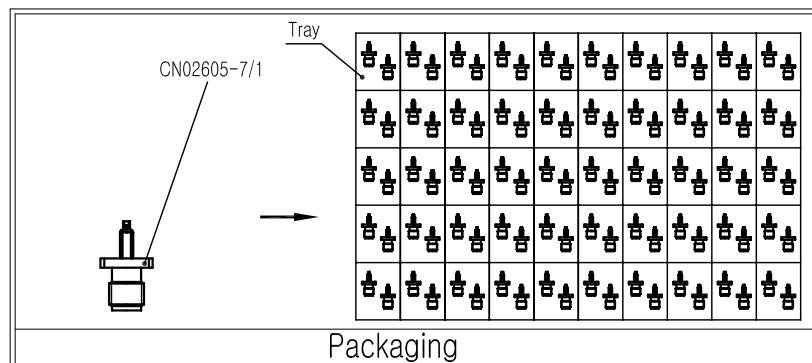
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	I.C.KIM	Y.H.CHOI	2010.10.14.



주 기

1. 포장 사양 - 완제품 조립후 Shrink tube를 절연체 위로 수축하여, 개별 비닐 포장후 Tray에 넣는다.

※※ 2. 내부 및 외부 비닐 포장, BOX 포장시 KJ 회사로고 없는 것으로 작업 할 것



4	SHRINK TUBE	1	—	—	ATU00052-N/1 (φ2-Black)
3	INSULATOR	1	TEFLON		DIN01842-N/1
2	CONTACT	1	BeCu	Gold Plate	DCT02355-5/1
1	BODY	1	MBsBD	Nickel Plate	DBD02837-5/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE 2010. 10. 14.		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle	APPROVED BY	Y.H.CHOI	
MATERIAL		CHECKED BY		TITLE SMA50 SOLDER END JS-4H
		DRAWN BY	I.C.KIM	
FINISH		SCALE	4/1	DWG NO. CN02605-7/1 REVISION I R SHEET 1 of 1
		UNIT	mm	

1 2 3 4 5 6